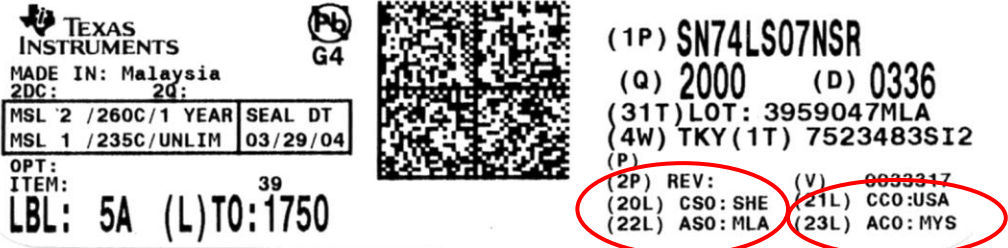


<b>PCN Number:</b>	20231207000.1		<b>PCN Date:</b>	December 07, 2023																			
<b>Title:</b>	Qualification of RFAB as an additional Fab site option for select ABCD6 devices																						
<b>Customer Contact:</b>	Change Management team		<b>Dept:</b>	Quality Services																			
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Mar 7, 2024		<b>Estimated Sample Availability:</b>	Jan 7, 2024*																			
<b>*Sample requests received after January 7, 2024 will not be supported.</b>																							
<b>Change Type:</b>																							
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material																					
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process																					
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input checked="" type="checkbox"/> Wafer Fab Site																					
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input checked="" type="checkbox"/> Wafer Fab Materials																					
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process																					
<b>PCN Details</b>																							
<b>Description of Change:</b>																							
Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option for the devices listed in the "Product Affected" section.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab Site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>MAINEFAB</td> <td>ABCD6</td> <td>200 mm</td> <td>RFAB</td> <td>ABCD6</td> <td>300 mm</td> </tr> </tbody> </table>			Current Fab Site			Additional Fab Site			Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter	MAINEFAB	ABCD6	200 mm	RFAB	ABCD6	300 mm			
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Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																		
MAINEFAB	ABCD6	200 mm	RFAB	ABCD6	300 mm																		
Qual details are provided in the Qual Data Section.																							
<b>Reason for Change:</b>																							
Continuity of supply																							
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																							
None																							
<b>Changes to product identification resulting from this PCN:</b>																							
<b>Fab Site Information:</b>																							
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Sample product shipping label (not actual product label)																							
																							
<b>Product Affected:</b>																							
DRV8350HRTVR	DRV8353FSRTAR	DRV8353HRTAR	DRV8353SRTAR																				
DRV8353FHRTAR	DRV8353HMRTAT	DRV8353SMRTAT																					

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8353HRTAR	QBS Reference: INA240A1EDRQ1	QBS Reference: INA240A2EDRQ1	QBS Reference: INA240A3EDRQ1	QBS Reference: DRV8353SRTAR	QBS Reference: DRV8353SRTAR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	1/77/0	1/77/0	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	1/77/0	1/77/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	1000 Hours	-	1/45/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	1/77/0
HTOL	B1	Life Test	150C	1000 Hours	-	1/77/0	1/77/0	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	150C	48 Hours	-	1/800/0	1/800/0	1/800/0	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	1/3/0	1/3/0	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	1/3/0	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: DRV8353HRTAR	QBS Reference: INA240A1EDRQ1	QBS Reference: INA240A2EDRQ1	QBS Reference: INA240A3EDRQ1	QBS Reference: DRV8353SRTAR	QBS Reference: DRV8353SRTAR
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2500 Volts	-	1/3/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/6/0	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/30/0	-	1/30/0	-	-

- QBS: Qual By Similarity
- Qual Device DRV8353HRTAR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2303-069

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV8350HRTVR	QBS Reference: INA240A1EDRQ1	QBS Reference: INA240A2EDRQ1	QBS Reference: INA240A3EDRQ1	QBS Reference: DRV8353HRTAR	QBS Reference: DRV8353SRTAR	QBS Reference: DRV8353SRTAR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	1/77/0	1/77/0	1/77/0	-	1/77/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	1/77/0	1/77/0	1/77/0	-	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	1/77/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	175C	1000 Hours	-	1/45/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	1/77/0
HTOL	B1	Life Test	150C	1000 Hours	-	1/77/0	1/77/0	1/77/0	-	-	-
ELFR	B2	Early Life Failure Rate	150C	48 Hours	-	1/800/0	1/800/0	1/800/0	-	-	-
ESD	E2	ESD CDM	-	1500 Volts	-	1/3/0	1/3/0	1/3/0	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	1000 Volts	-	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2500 Volts	-	1/3/0	-	-	-	-	-

Type	#	Test Name	Condition	Duration	Qual Device: DRV8350HRTVR	QBS Reference: INA240A1EDRQ1	QBS Reference: INA240A2EDRQ1	QBS Reference: INA240A3EDRQ1	QBS Reference: DRV8353HRTAR	QBS Reference: DRV8353SRTAR	QBS Reference: DRV8353SRTAR
LU	E4	Latch-Up	Per JESD78	-	-	1/6/0	1/6/0	1/6/0	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0	1/30/0	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot and cold	-	-	1/30/0	-	1/30/0	-	-	-

- QBS: Qual By Similarity
- Qual Device DRV8350HRTVR is qualified at MSL2 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2305-023

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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